



App. No. 10/762,143
Amendment dated Aug. 10, 2005
Reply to Office Action of May 10, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listing, of claims in the application:

Listing of Claims:

Claim 1 (original): Apparatus, comprising:

- a) a layer of dielectric;
- b) a plurality of conductors;
- c) a plurality of dielectric mounds, wherein each of the conductors is encapsulated between the layer of dielectric and a corresponding one of the dielectric mounds; and
- d) a first ground shield positioned below the layer of dielectric, and a second ground shield positioned above the dielectric mounds.

Claim 2 (original): The apparatus of claim 1, wherein the second ground shield is deposited on the dielectric mounds.

Claim 3 (original): The apparatus of claim 2, further comprising a plurality of conductive vias in the layer of dielectric; the conductive vias coupling the first and second ground shields at points about the plurality of conductors.

Claim 4 (original): The apparatus of claim 3, further comprising a plurality of ground pads deposited on the layer of dielectric; the ground pads providing a means for coupling the second ground shield to the conductive vias.

Claim 5 (original): The apparatus of claim 2, further comprising a plurality of ground traces deposited on the layer of dielectric; the ground traces providing a means for coupling the second ground shield to the conductive vias.

Claim 6 (original): The apparatus of claim 1, wherein at least some of the dielectric mounds are separated from one another by a distance that is less than a width of one of the dielectric mounds.

Claim 7 (original): The apparatus of claim 1, wherein at least some of the dielectric mounds are substantially adjacent one another.

Claim 8 (currently amended): The apparatus of claim 1, wherein the layer of dielectric and the dielectric mounds are glass dielectrics.

Claim 9 (currently amended): The apparatus of claim 1, wherein the layer of dielectric and the dielectric mounds are ~~[[KQ]]~~ceramic dielectrics.

Claim 10 (currently amended): The apparatus of claim ~~[[9]]~~1, wherein the ~~KQ dielectrics~~layer of dielectric and dielectric mounds are KQ CL-90-7858 dielectrics.

Claim 11 (currently amended): The apparatus of claim 1, wherein the layer of dielectric and the dielectric mounds are thickfilm dielectrics.

Claim 12 (original): The apparatus of claim 1, further comprising a substrate; the first ground shield being deposited on the substrate, and the layer of dielectric being deposited on the first ground shield.

Claim 13 (currently amended): The apparatus of claim 1, wherein the conductors and second ground shield comprise ~~[[DuPont® QG150 gold]]~~a thickfilm conductive paste.

Claim 14 (currently amended): The apparatus of claim 1, wherein the layer of dielectric, the dielectric mounds, the plurality of conductors, and the second ground shield comprise thickfilms.

Claim 15 (currently amended): A method for forming transmission lines, comprising:

- a) depositing a plurality of conductors on a layer of dielectric that is positioned above a first ground shield;
- b) depositing a respective mound of dielectric over each conductor; and
- c) depositing a second ground shield over the mounds of dielectric.

Claim 16 (original): The method of claim 15, further comprising, prior to depositing the mounds of dielectric, forming a plurality of conductive vias in the layer of dielectric, at points about the plurality of conductors; the conductive vias contacting the first ground shield; wherein the mounds of dielectric and second ground shield are deposited to ensure contact between the second ground shield and conductive vias.

Claim 17 (original): The method of claim 16, further comprising, prior to depositing the mounds of dielectric, depositing a plurality of ground pads on the layer of dielectric; the ground pads contacting the conductive vias.

Claim 18 (original): The method of claim 16, further comprising, prior to depositing the mounds of dielectric, depositing a plurality of ground traces on the layer of dielectric; the ground traces contacting the conductive vias.

Claim 19 (currently amended): The method of claim 15, wherein the layer of dielectric and the mounds of dielectric are KQ CL-90-7858 dielectrics.

Claim 20 (currently amended): The method of claim 19, wherein each of i) the ~~dielectrics~~ layer of dielectric, and ii) the mounds of dielectric, are deposited by printing multiple layers of thickfilm dielectric and then firing the layers.